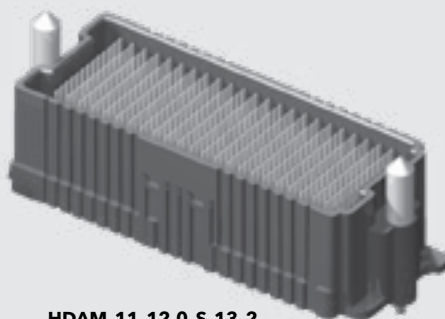
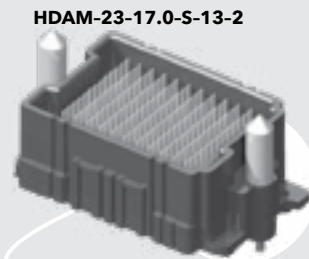




(2.00 mm) .0787"



HDAM-11-12.0-S-13-2



HDAM-23-17.0-S-13-2

HDAM SERIES

# RUGGED ELEVATED HIGH-DENSITY ARRAY

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HDAM](http://www.samtec.com?HDAM)

### Insulator Material:

Black LCP

### Contact Material:

Copper Alloy

### Plating:

Au or Sn over

50  $\mu$ " (1.27  $\mu$ m) Ni

### Current Rating:

3.4 A per pin

(6 adjacent pins powered)

### Operating Temp Range:

-55 °C to +125 °C

### Working Voltage:

200 VAC

### Mated Cycles:

100

### RoHS Compliant:

Yes

### Lead-Free Solderable:

Yes

Mates with:  
HDAF

Intermateable with  
Molex HD Mezz

Open-pin-field for  
Single-Ended or  
Differential Pair  
configurations

Lead-Free  
Solder Charge

299, 195  
and 143 pins

Elevated stack heights  
of 20 mm, 25 mm,  
30 mm and 35 mm

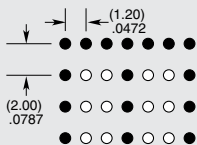
## RECOGNITIONS

For complete scope of  
recognitions see  
[www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

\*2:1 S:G Ratio

## ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
- Other platings

### Notes:

HD Mezz is a trademark of  
Molex Incorporated

Some lengths, styles and  
options are non-standard,  
non-returnable.

